



Chengdu

KEY SERVICES

- 8" Wafer Bumping & WLCSP Services
- Wafer Probe and Bump Probe
- Wafer Backgrinding
- Assembly of Leadframe, Array and Leadless packages
- Final Test including RF, Analog and Mixed Signal
- Tape and Reel
- Drop Shipping and Distribution

KEY FACTS

- Factory Floor Space:
520,000 ft² (48,310 m²)
- Equipment Capacity:
8.5 million units/capacity a day
- Employees: 2,000

TEST PLATFORMS

- Linear/Analog
- High-end RF
- Mixed Signal
- VLSI

PACKAGE PORTFOLIO

- Array Packages - LGA, FC-LGA, FBGA, MEMS
- Leadframe Packages - MSOP, SOIC, FC-SOIC
- Leadless Packages - DFN/QFN, FC-QFN, WLCSP
- Modules / SIP

CERTIFICATIONS

- ISO 14001:2004
- ISO 9001:2008
- ISO/TS 16949:2009
- Certificate of Green Partner (Sony)
- OHSAS 18001:2007
- ANSI ESD S20.20

